	<b>SPIRE BSM Declared Process List</b> <b>Procedure ID SPI-BSM-PRJ-708 ITEM #18</b> <b>Version no 1.1</b>	Ref: SPI-BSM-NOT-0029 Page : Page 1 of 4 Date : 17/06/04 Author: KW
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**SPIRE BSM Declared Processes**  
**Procedure ID SPI-BSM-PRJ-708 ITEM 18**  
***Cleaning Components***

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<b>Date:</b>	17/06/04
<b>Version:</b>	1.1

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### Version Control

Date	Index	Remarks
29/11/02	1.0	Issue to tie in with DPL
17/06/04	1.1	DPL, DML and PA plan revision change

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***Applicable documents***

Applicable documents are project specific and may be assumed to apply fully to the BSM, unless stated otherwise

<b>Ref</b>	<b>Title</b>	<b>Author</b>	<b>Reference</b>	<b>Date</b>
AD 1	SPIRE BSM Declared Process List v 1.6	IP	SPI-BSM-PRJ-0708	15/06/04
AD 2	SPIRE ATC PA PLAN v1.5	BCG	SPI-BSM-PRJ-0711	09/06/03
AD 3				
AD 4				


***Reference documents***

Reference documents are generic and may only apply in part to the project, or may be for information or reference only.

<b>Ref</b>	<b>Title</b>	<b>Author</b>	<b>Reference</b>	<b>Date</b>
RD 1	SPIRE BSM Declared Materials List v1.5	IP	SPI-BSM-PRJ-0710	15/06/04
RD 2				
RD 3				
RD 4				

***Glossary***

**Refer to:** [http://www.roe.ac.uk/atc/projects/spire/SPIRE\\_BSM\\_Glossary.html](http://www.roe.ac.uk/atc/projects/spire/SPIRE_BSM_Glossary.html)

	<p align="center"><b>SPIRE BSM Declared Process List</b></p> <p align="center">Procedure ID SPI-BSM-PRJ-708 ITEM #18</p> <p align="center">Version no 1.1</p>	<p>Ref: SPI-BSM-NOT-0029</p> <p>Page : Page 4 of 4</p> <p>Date : 17/06/04</p> <p>Author: KW</p>
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## 1 SCOPE

## 2 INTRODUCTION

## 3 PROCESS      CLEAN COMPONENTS BEFORE ASSEMBLY

### 3.1 Ultrasonic clean components and rinse in hot running water.

Handle wearing protective gloves.

Dry in oven at a maximum temperature of 50 degrees C for 10 minutes.

Place in sealable bag and store until required.

Note:- components with magnets attached need to be examined under a microscope and any magnetic particles stuck to the magnets must be removed with tweezers.

No amount of ultrasonic cleaning or washing will remove these particles.